

ABSTRACT

5

WET-TACK SINTERING METHOD AND APPARATUS

10 Prior to sintering a component to a carrier, a portion of a sintering surface at or adjacent
to a first side of the component is caused to contact a sintering paste applied on the
carrier when a second side of the component that is opposite to the first side is
supported by a support mechanism, such that the sintering surface of the component
is tilted relative to the carrier. The support member is then moved to gradually reduce
a distance between the second side of the component and the carrier so as to cause
a remainder of the sintering surface of the component to contact the sintering paste.
15 Therefore, air that is present between the component and the sintering paste may be
removed before the component is sintered to the carrier.

[FIG. 2]